

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MYONG WOON KIM	05/10/2021
SANG ICK LEE	05/12/2021
JANG WOO SEO	05/12/2021
SANG YONG JEON	05/10/2021
HAENG DON LIM	05/10/2021
RECEIVING PARTY DATA	
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Postal Code:	34366
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17294377
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DATE SIGNED:	05/19/2021
Total Attachments: 2	
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ASSIGNMENT

WHEREAS, we, the following named inventors:

- 1. Myong Woon KIM, residing in Daejeon, Republic of Korea;
- 2. Sang Ick LEE, residing in Daejeon, Republic of Korea;
- 3. Jang Woo SEO, residing in Daejeon, Republic of Korea;
- 4. Sang Yong JEON, residing in Sejong-si, Republic of Korea; and
- 5. Haeng Don LIM, residing in Daejeon, Republic of Korea;

have invented an invention entitled **METHOD FOR MANUFACTURING MOLYBDENUM-CONTAINING THIN FILM AND MOLYBDENUMCONTAINING-THIN FILM MANUFACTURED THEREBY**, for which we have executed an application for Letters Patent of the United States (check one):

- on the date we executed this assignment;
- as U.S. Patent Application No. 17/294,377, filed May 14, 2021;
- as International Application No. _____, filed _____;

we authorize the attorneys/agents authorized to act under Customer Number 145572 to insert the filing date and application number of said application when known.

WHEREAS, DNF CO., LTD. ("Assignee"), a Republic of Korea organization, having its principal place of business at 142, Daehwa-ro 132beon-gil, Daedeok-Gu, Daejeon, 34366 Republic of Korea, is desirous of acquiring an interest therein;


NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, we, the above named inventors, have sold, assigned, and transferred, and by these presents do sell, assign, and transfer unto Assignee, the full and exclusive right to the above-identified invention in the United States and its territorial possessions and in all foreign countries, and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States and its territorial possessions and in any and all foreign countries, and in and to any and all divisions, reissues, continuations and extensions thereof, and all priority rights under all present or future conventions and treaties, and any provisional applications for which priority is claimed.

We hereby authorize and request the Patent Office officials in the United States and any and all foreign countries to issue any and all of said Letters Patent, when granted, to Assignee, as the assignee of our entire right, title and interest in and to the same, for the sole use of the Assignee, their successors and assigns.

Further, we agree that we will communicate to Assignee, or their representatives, any facts known to us respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitution, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to Assignee, make all rightful oaths and generally do everything possible to aid Assignee, their successors and assigns, to obtain and enforce proper protection for said invention in the United States and in any and all foreign countries.

IN TESTIMONY WHEREOF, we have hereunto set our hands on the dates indicated below.

- 1. Inventor Name: Myong Woon KIM Signature: [Signature] Date: 2021/5/10
- 2. Inventor Name: Sang Ick LEE Signature: [Signature] Date: 2021/5/12
- 3. Inventor Name: Jang Woo SEO Signature: [Signature] Date: 2021/5/12
- 4. Inventor Name: Sang Yong JEON Signature: [Signature] Date: 2021/05/10

5. Inventor Name: Haeng Don LIM Signature:  Date: 2021/05/10